2SC4655

Silicon NPN epitaxial planar type

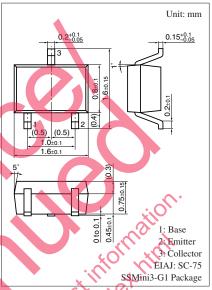
For high-frequency amplification

■ Features

- Optimum for RF amplification, oscillation, mixing, and IF of FM/AM radios
- SS-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

■ Absolute Maximum Ratings $T_a = 25$ °C

Symbol	Rating	Unit
V_{CBO}	30	V
V_{CEO}	20	V
V_{EBO}	5	V
Ic	30	mA
P _C	125	mW
T_{j}	125	°C
T _{stg}	-55 to +1 25	°C
	$\begin{array}{c} V_{CBO} \\ V_{CEO} \\ V_{EBO} \\ I_{C} \\ \hline P_{C} \\ T_{j} \end{array}$	V _{CBO} 30 V _{CEO} 20 V _{EBO} 5 I _C 30 P _C 125 T _j 125



Marking Symbol: K

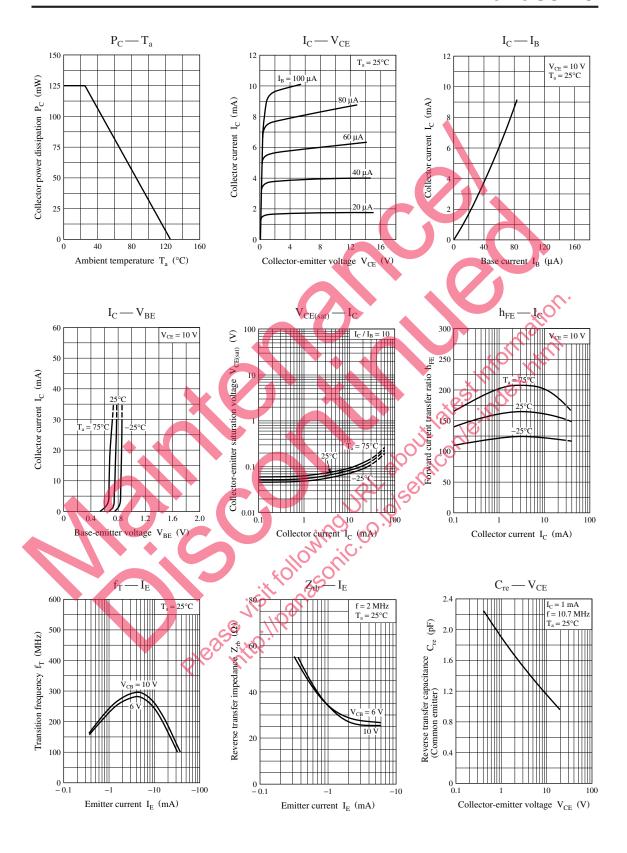
■ Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = 10 \mu \text{A}, I_{\rm B} = 0$	30			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_C = 2 \text{ mA}, I_B = 0$	20			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_{\rm H} = 10 \mu{\rm A}, I_{\rm C} = 0$	5			V
Forward current transfer ratio *	h_{FE}	$V_{CE} = 10 \text{ V}, I_{C} = 1 \text{ mA}$	70		250	_
Transition frequency	f_T	$V_{CB} = 10 \text{ V}, I_E = -1 \text{ mA}, f = 200 \text{ MHz}$	150	230		MHz
Reverse transfer capacitance	Cre	$V_{CB} = 10 \text{ V}, I_E = -1 \text{ mA}, f = 10.7 \text{ MHz}$		1.3		pF
(Common emitter)	2 X	p.,				

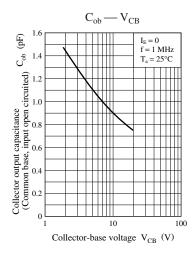
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

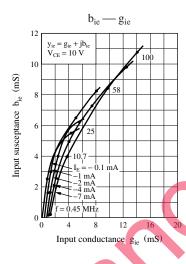
2. *: Rank classification

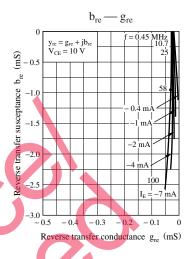
Rank	В	С
h_{FE}	70 to 160	110 to 250

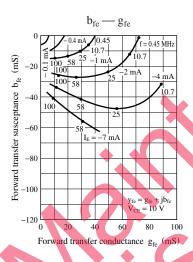


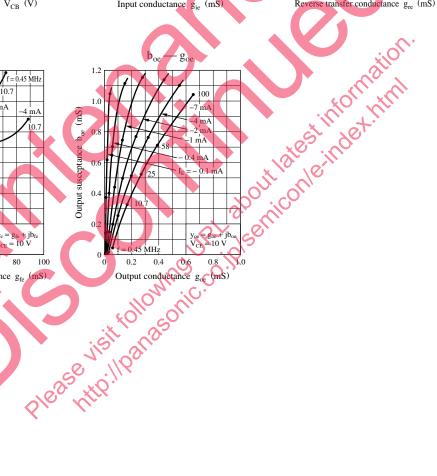
Panasonic 2SC4655











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